EFFICIENCY IMPROVEMENT IN TiO$_2$-PARTICLE BASED SOLAR CELLS AFTER DEPOSITION OF METAL IN SPACES BETWEEN PARTICLES

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We report the fabrication of solar cells employing TiO$_2$ particles as the active light-absorbing material. The solar cells were prepared by depositing TiO$_2$ particles on a transparent conducting electrode (ITO), followed by a polymer electrolyte and a counter electrode. Copper particles were deposited in the spaces between the particles prior to deposition of the polymer electrolyte, forming continuous copper bridges to quickly transport generated photoelectrons from the particle surfaces to the transparent electrode, reducing electron/hole recombination. Several metal deposition methods were used including sputtering, electroplating, and doctor-blade coating. This strategy resulted in significant enhancement of the solar conversion efficiency compared to a similar design constructed without the copper coating.

**Keywords:** metal-semiconductor junction, performance and solar cells.

INTRODUCTION

TiO$_2$ is widely used in solar energy applications such as photovoltaic cells (Grätzel, 2003; Ribiero, et al., 2009; Wang et al., 2009; Tachibana et al., 2008; Singh et al., 2009), air and water purification (Birnie et al., 2006; Kabra et al., 2009; Hashimoto et al., 2005) and UV absorption in cosmetics (Jaroenworaluck et al., 2006). It has been employed in dye sensitized solar cells (DSSC) and bulk heterojunction solar cells (BHJ) to obtain high conversion efficiencies (Chiba et al., 2006) coupled with easy fabrication (Huang et al., 2007), low cost (O’Regan et al., 1991; Joshi et al., 2009), low toxicity (Sommeling et al., 2004), and long-term stability (HaiLing et al., 2009). However, the rapid rate of electron-hole recombination on TiO$_2$ particles (Figure 1) makes the efficiency of TiO$_2$-based solar cells without dyes quite low.

![Figure 1](a) Photoexcitation process on TiO$_2$ surface and (b) Design of solar cells.
Several recent reports have described efficiency enhancements in TiO$_2$ solar cells. A popular method is to minimize electron-hole recombination by depositing metal on the semiconductor surface (Pan et al., 2007; Cai et al., 2008; Subramanian et al., 2004; Behnajady et al., 2008; Chen et al., 2007; Subramanian et al., 2001; Gnaser et al., 2004; Diebolt, 2003; Wang et al., 2008; Hajkova et al., 2009; Grabowska et al., 2010; Linsebigler et al., 1995). The excited electrons are trapped at the metal surface, increasing charge carrier lifetimes.

In order to decrease recombination of electron-hole pairs and increase quantum efficiency of the photocatalytic process, we modified TiO$_2$ thin films using an interconnected metal (Cu) for electron transport (Figure 1b) (Sommeling et al., 2004; Fuke et al., 2007). The cells employed a polymer electrolyte composed of polyethylene glycol and a lithium salt for hole transport and to increase the short circuit current (Wang et al., 2008; Wu et al., 2008; Jiang et al., 2003; Kang et al., 2005). The copper was deposited using sputtering, doctor-blade coating, or electroplating. We also investigated the effect of metal particle size on cell performance. A subsidiary goal of the study was to demonstrate the use of simple and low-cost methods such as electroplating for depositing metal on TiO$_2$ surfaces.

**EXPERIMENTAL**

**Materials**

TiO$_2$ was purchased from Bratachem, Indonesia. Cu$_2$SO$_4$, copper powder, lithium hydroxide monohydrate (LiOH), and polyethylene glycol (PEG, $n=20,000$) were purchased from Merck, Indonesia. ITO with a sheet resistance of 100 $\Omega$/cm$^2$ was purchased from Solaronix, Switzerland.

**Preparation of copper-coated TiO$_2$ nanoparticles**

**Sputtering methods**

The deposition parameters for fabrication of Cu/TiO$_2$ structures are summarized in Table 1.

**Table 1** Deposition parameters for Cu/TiO$_2$ structures.

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Value</th>
</tr>
</thead>
<tbody>
<tr>
<td>Flow rate of Ar, sccm</td>
<td>100</td>
</tr>
<tr>
<td>Heater temperature, °C</td>
<td>150</td>
</tr>
<tr>
<td>Pressure, Bar</td>
<td>0.71</td>
</tr>
<tr>
<td>Time deposition, sec</td>
<td>300</td>
</tr>
<tr>
<td>$I_{\text{Plasma}}$, mA</td>
<td>39</td>
</tr>
<tr>
<td>$V_{\text{Plasma}}$, V</td>
<td>600</td>
</tr>
</tbody>
</table>

**Electroplating methods**

Copper coatings were prepared using a Watts-type bath containing 20 mL copper sulfate (Cu$_2$SO$_4$). A copper rod of 99.99% purity with dimensions of 5 cm was used as the anode and the TiO$_2$ film deposited on an ITO-coated glass substrate was used as the cathode. The electroplating conditions are listed in Table 2.
Table 2  Electroplating conditions for Cu coating.

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Value</th>
</tr>
</thead>
<tbody>
<tr>
<td>Current, A</td>
<td>1.0</td>
</tr>
<tr>
<td>Voltage, V</td>
<td>5.0</td>
</tr>
<tr>
<td>Deposition time, s</td>
<td>10.0</td>
</tr>
<tr>
<td>Solution concentration, M</td>
<td>0.1</td>
</tr>
<tr>
<td>Volume of solution, mL</td>
<td>20.0</td>
</tr>
<tr>
<td>Distance anode-cathode, cm</td>
<td>5.0</td>
</tr>
<tr>
<td>ITO resistance, Ω/cm²</td>
<td>100</td>
</tr>
<tr>
<td>Bath temperature, °C</td>
<td>25</td>
</tr>
</tbody>
</table>

Doctor-blade methods

Nanocomposites were prepared by dissolving 0.7 g PEG in 10 mL of water at 80°C for 2 hours, then adding 1 g TiO₂ and 0.1 g Cu and stirring until gelation occurred. The Cu/TiO₂ nanocomposites were deposited on an ITO-coated glass substrate by applying the doctor-blade technique. The films were heated on a hot plate at 80°C for 5 min. The process is illustrated in Figure 2.
Figure 2  Doctor-blade coating process for producing Cu/TiO$_2$ nanocomposite films.

Characterization of TiO$_2$ films

The optical absorbance of the films was determined using a Cary 100 UV/Vis spectrometer. The surface morphology and film composition were examined using a JEOL JSM-6360LA SEM equipped with an EDX attachment. The structure of the films was investigated using XRD on a PW1710 diffractometer.

Procedures
The solar cells consisted of an ITO electrode, a TiO$_2$ layer coated with metal (Cu), a gel polymer electrolyte layer, and an Al counter electrode.

The ITO-coated glass substrate (1 cm$^2$) was sonicated in water for 15 min, followed by 70% alcohol for 30 min. A suspension was prepared by dispersing 10 g TiO$_2$ in 10 mL of water and mixing with a magnetic stirrer for 45 min. The TiO$_2$ suspension was sprayed on the substrate at a temperature of 150 °C (Halme et al., 2006). The spray process was repeated 30 times. The resulting thick film of TiO$_2$ was heated on a hot plate at 250 °C for 30 min to evaporate water, then sintered at 450 °C for 30 min to improve the electrical contact between the TiO$_2$ particles and the ITO. The films were then coated with Cu.

The polymer electrolyte was made by dissolving 0.5 g LiOH (Bratachem, Indonesia) in 10 mL water and adding 0.8 g polyethylene glycol (PEG, Merck). The mixture was heated with stirring at
110 °C for 1 hour to produce a gel-like electrolyte. The electrolyte was manually applied to the Cu/TiO$_2$ layer and an aluminum counter electrode was added.

RESULTS AND DISCUSSION

Characterization of TiO$_2$ and Cu-coated TiO$_2$ films

The UV-Vis spectrum of a TiO$_2$ electrode is presented in Figure 3(a). The electrode absorbs over a very broad range, from less than 200 nm to more than 800 nm, in contrast to the pure TiO$_2$ spectrum of Figure 3(b). The broad absorption spectrum suggests these devices are potentially excellent solar harvesting devices.

![Figure 3](image)

**Figure 3** Absorption spectra of modified (a) and pure (b) TiO$_2$ films.

The morphology of TiO$_2$ was determined using electron dispersive X-ray analysis and SEM. The particles are sub-micrometer in size, with a minimum value of approximately 192 nm. Figure 4(a) is a micrograph of the TiO$_2$ electrode. The film surface is smooth and uniform with equally distributed nanometer sized grains. According to the theory of Usami and Ozaki the grains could also improve conversion efficiency through multiple scattering events (Bi-Tao et al., 2008).

![Figure 4](image)

**Figure 4** SEM images of TiO$_2$ film without Cu nanoparticles: (a) surface and (b) cross section.
The porous TiO$_2$ electrode formed using the spray method provides pore sizes of 50-300 nm and a thickness of 5-6 µm. Figure 4(b) is a cross-sectional view of the film. It is expected that during electroplating nucleation of Cu nanoparticles begins in the pores of TiO$_2$. Inside the film there is not much difference in grain size between TiO$_2$ and Cu.

Figure 5  Surface and cross-section of Cu/TiO$_2$ films after coating using: electroplating methods (a,b), doctor-blade (c,d), and sputtering (e,f).

Figures 5(a) and (b) illustrate the Cu films grown in the pores and on the surface of the TiO$_2$ film using electroplating. The diamond-shaped Cu grains are larger than the TiO$_2$ particles and make
contact with each other. It is assumed that the excited electrons generated in the TiO$_2$ are trapped in the Cu particles. Figures 5(c) and (d) are images of the Cu/TiO$_2$ nanocomposite film formed using the doctor-blade method. The bulk Cu is in contact with the TiO$_2$ particles. Conversely, SEM images of Cu/TiO$_2$ structures prepared using sputtering (Figures 5(e) and (f)) reveal that the Cu distribution is not uniform and that the deposit consists of isolated small grains of Cu in contact with TiO$_2$ particles.

**Figure 6** Elemental analysis of TiO$_2$ films: (a) Uncoated TiO$_2$, (b) Cu/TiO$_2$ (doctor-blade), (c) Cu/TiO$_2$ (sputtering), and (d) Cu/TiO$_2$ (electroplating)

Elemental analyses of TiO$_2$ films based on EDX analysis were also performed using the JEOL JSM-6360LA. Figure 6 contains the EDX spectra of uncoated and coated TiO$_2$. The peaks in figure 6(a) correspond to Ti and O, demonstrating that the film is essentially pure. Figures 6(b), (c), and (d) display Cu peaks, indicating that the TiO$_2$ films were successfully coated with Cu to the extent of 53.27%, 26.36%, or 40.86%.
Figure 7 X-ray diffraction pattern of: (a) Uncoated TiO$_2$, (b) Cu/TiO$_2$ (electroplating), (c) Cu/TiO$_2$ (doctor-blade), and (d) Cu/TiO$_2$ (sputtering).

The XRD patterns of pure and Cu-coated TiO$_2$ nanoparticles appear in Figure 7, for 2$\theta$ diffraction angles between 10° and 90°. The XRD pattern of TiO$_2$ exhibits primary peaks at 25°, 38°, 49°, and 83°, which may be attributed to the diffraction planes of anatase TiO$_2$. The two peaks at 40° and 52° may be attributed to the diffraction planes of Cu.

The average size (D) of the Cu particles was determined from the XRD patterns of several Cu/TiO$_2$ samples (Figure 7) using Scherer’s equation (Table 3).

\[ D = \frac{k \lambda}{\beta \cos \theta} \]  \hspace{1cm} (1)
In this equation, $k$ is a constant equal to 0.9, $\lambda$ is the x-ray wavelength (equal to 0.154 nm), $\beta$ is the full width of the peak at half-maximum, and $\theta$ is half of the diffraction angle (Abdullah et al., 2010).

**Effect of Cu coating on cell performance**

The performance of the devices was measured using a current-voltage (I-V) meter (Keithley 617). The measurements were obtained in the dark and under xenon lamp illumination. Light intensity was measured using a luxmeter (Lutron LX-101). The results depicted in figure 8 indicate that the interlayer electrical connections are well-developed.

The performance was characterized under AM 1.5 illumination at high ($37.48 \text{ mW/cm}^2$) and low ($4.39 \text{ mW/cm}^2$) intensities. The efficiency $\eta$ under xenon illumination was calculated using $\eta = \left( \frac{V_{oc} \cdot I_{sc} \cdot FF}{P_{in}} \right) \times 100\%$, in which $V_{oc}$ is the open-circuit voltage, $I_{sc}$ is the short-circuit current, $FF$ is the fill factor, and $P_{in}$ is the total radiant power received by the cell.

The efficiencies of the solar cells described here were greater than the results of our previous study (Abdullah et al., 2010; Saehana et al., 2010), but the FF was still very low. Under intense irradiation, the efficiencies were approximately 1.20%, 0.40%, and 0.78%. Under lower intensity illumination, the efficiencies were 0.82%, 0.39%, and 0.60%. The poor performance may be due to the poor fill factor, short-circuit current, or open-circuit voltage, which in turn may be affected by the high sheet resistance of TiO$_2$ films (Ahn et al., 2007; Han et al., 2006).

The results illustrated in figure 8 clearly indicate that the performance of Cu/TiO$_2$ film devices is greater than devices employing uncoated TiO$_2$ films. This is caused by the high Schottky
electron transfer processes. According to Hailing (2009), electron capture by metals increases electron-hole pair separation lifetime by hindering the recombination of electron-hole pairs and promoting interfacial electron transfer processes.

Figure 9(a) is a schematic diagram depicting an electron trapped at the Schottky barrier of a metal/semiconductor interface, highlighting the small area of the semiconductor surface actually covered by the metal. In scheme 9(a), the excited electron moves to the metal and becomes trapped, reducing electron-hole recombination. The migration of electrons to the metal particles was confirmed by studies indicating a reduction in the photoconductance of the semiconductor in Cu/TiO2 devices compared to those using TiO2 alone (Linsebigler et al., 1995). Figure 9(b) contains the band diagram of a metal and semiconductor in contact at equilibrium, in which electrons flow to the metal from the semiconductor.

![Figure 9](image)

**Figure 9** (a) Mechanism of photoexcitation process in Cu-deposited TiO2 under UV irradiation, and (b) band diagram of metal-semiconductor (Schottky) junction at equilibrium.

Electronic modification of the semiconductor surface via metal deposition has been observed with other noble metals such as Pt, Ag, and Au. The addition of metal to the TiO2 surface may cause trapping of electrons at the metal sites (Diebolt, 2003; Duncan et al., 2007).

The results plotted in Figure 10 also demonstrate that the performance of Cu/TiO2 sputtered films was higher devices produced using electroplating or doctor-blade methods. The difference in performance may be caused by the particle size and distribution of copper on the TiO2 film.

### Effect of Copper Size and Content on Performance of Solar Cell

The performance of the Cu/TiO2 composite system was initially enhanced with increasing Cu content (HaiLing et al., 2009), but decreased after reaching a critical Cu loading value due to bulk effects. Copper has a high work function and displays a stronger bulk effect than materials such as Au, Ag, and Pt. Large metal particle sizes decreased the performance of the cells.

The electron affinity of copper is 119.24 kJ/mol and the work function is 4.65 eV. The ability of a metal to accept an electron from a semiconductor is related to the electron affinity, with higher affinity metals more easily accepting electrons. Conversely, the work function describes the facility of electron migration from the interior to the surface of a metal, with smaller values indicating easier migration. A synergistic tradeoff between these two values determines the performance of this type of solar cell. However, copper is a relatively cheap metal, and surface modification with Cu still improves TiO2 thin-film performance.
Table 3  Comparison between Cu/TiO₂ solar cells fabricated using sputtering, electroplating, and doctor-blade methods.

<table>
<thead>
<tr>
<th>Copper Deposition Method</th>
<th>Mass Content of Cu, %</th>
<th>Grain Size of Cu, nm</th>
<th>Efficiency of Solar Cells, %</th>
</tr>
</thead>
<tbody>
<tr>
<td>Sputtering</td>
<td>26.36</td>
<td>78.42</td>
<td>1.20</td>
</tr>
<tr>
<td>Electroplating</td>
<td>42.40</td>
<td>228.75</td>
<td>0.78</td>
</tr>
<tr>
<td>Doctor-Blade</td>
<td>53.27</td>
<td>1,863</td>
<td>0.40</td>
</tr>
</tbody>
</table>

Cu/TiO₂ solar cells coated using sputtering displayed higher efficiencies than other methods. This may be an effect of grain size (Rashidi et al., 2010), the high doping content (Subramanian et al., 2004), or the large fraction of metal deposited on the surface causing electron accumulation on the particles and lower quantum efficiency. However, the electroplating method has potential for further development and improvement through parameter optimization.

Effect of Polymer Electrolyte on Performance

We also investigated the use of a polymer electrolyte containing Li⁺ to improve the device stability and prevent solvent evaporation. The use of a gel polymer electrolyte with a conductivity of 0.16 S/cm also increased the speed of electron migration in TiO₂ and enhanced the short-circuit current and open-circuit voltage of the solar cells (Wu et al., 2008; Aravindan et al., 2007). According to Wang et al. (2008), Li⁺ ion creates new trapping states that contribute to electron injection into the TiO₂ conduction band. Increases in electrolyte conductivity increase the short-circuit current. However, in this study conductivity optimization was not performed.

CONCLUSION

Copper coated TiO₂ films were more efficient than uncoated TiO₂ films in terms of photovoltaic activity. This may be the result of a well-developed metal-semiconductor junction (Schottky junction) hindering electron-hole recombination. Considering metal bulk effects, we also found that the efficiency of solar cells prepared using a sputtering method was higher than those constructed using electroplating or doctor-blade methods, possibly because of grain size or copper content.

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